

Integrated Circuit Bond Pad Structures
and Methods of Making
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Serial No.: 10/694,675

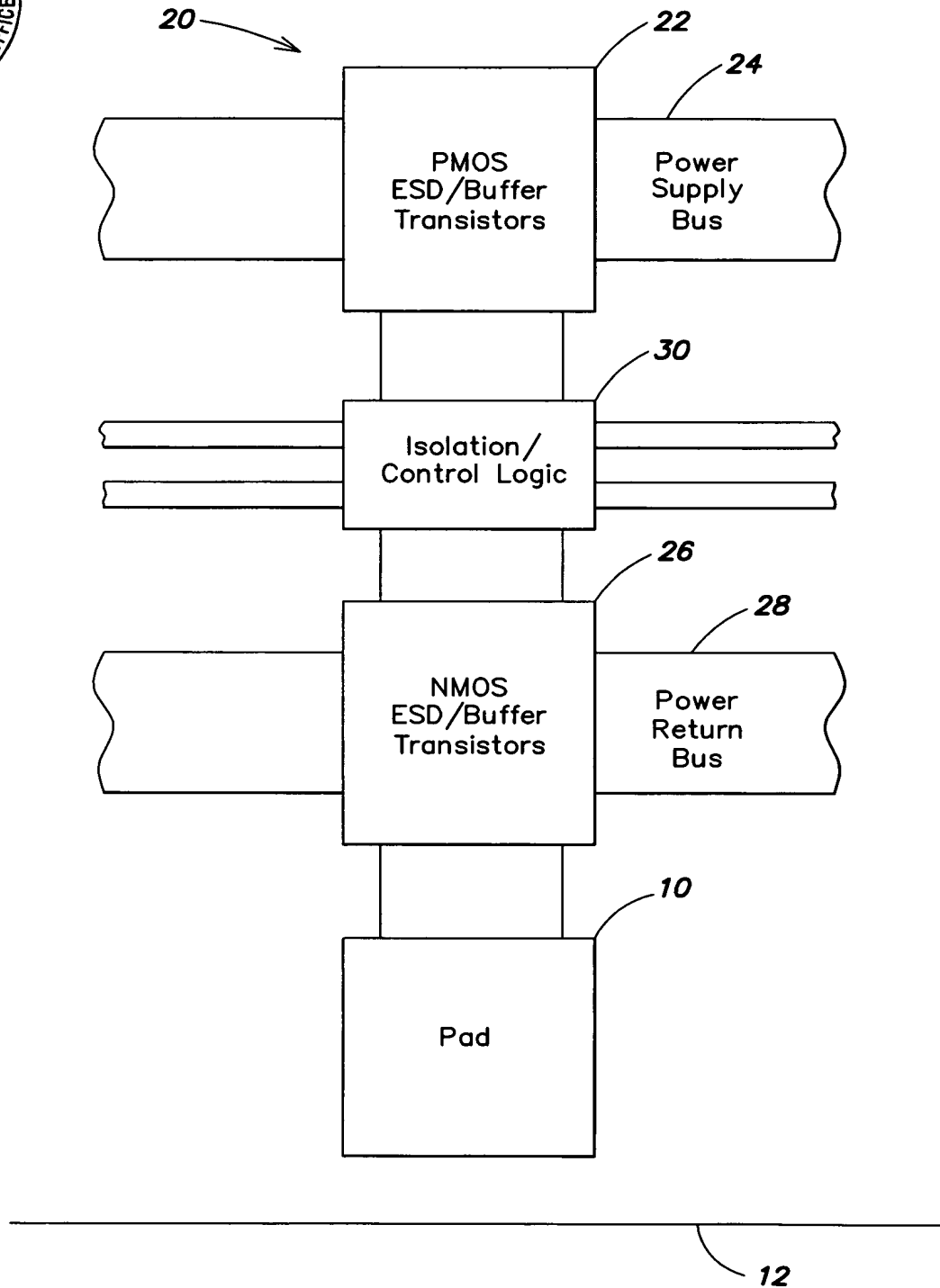


FIG. 1
(Prior Art)

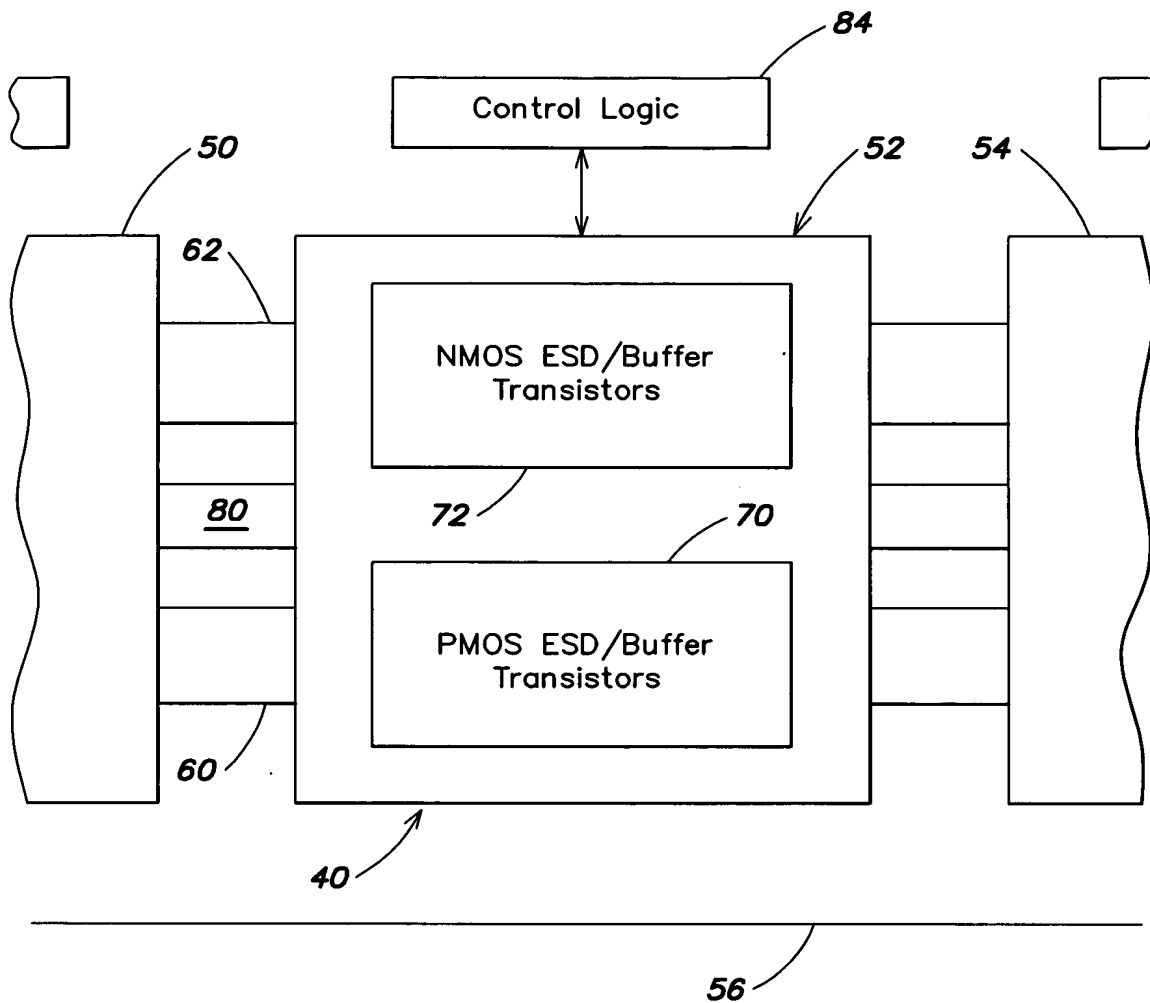


FIG. 2

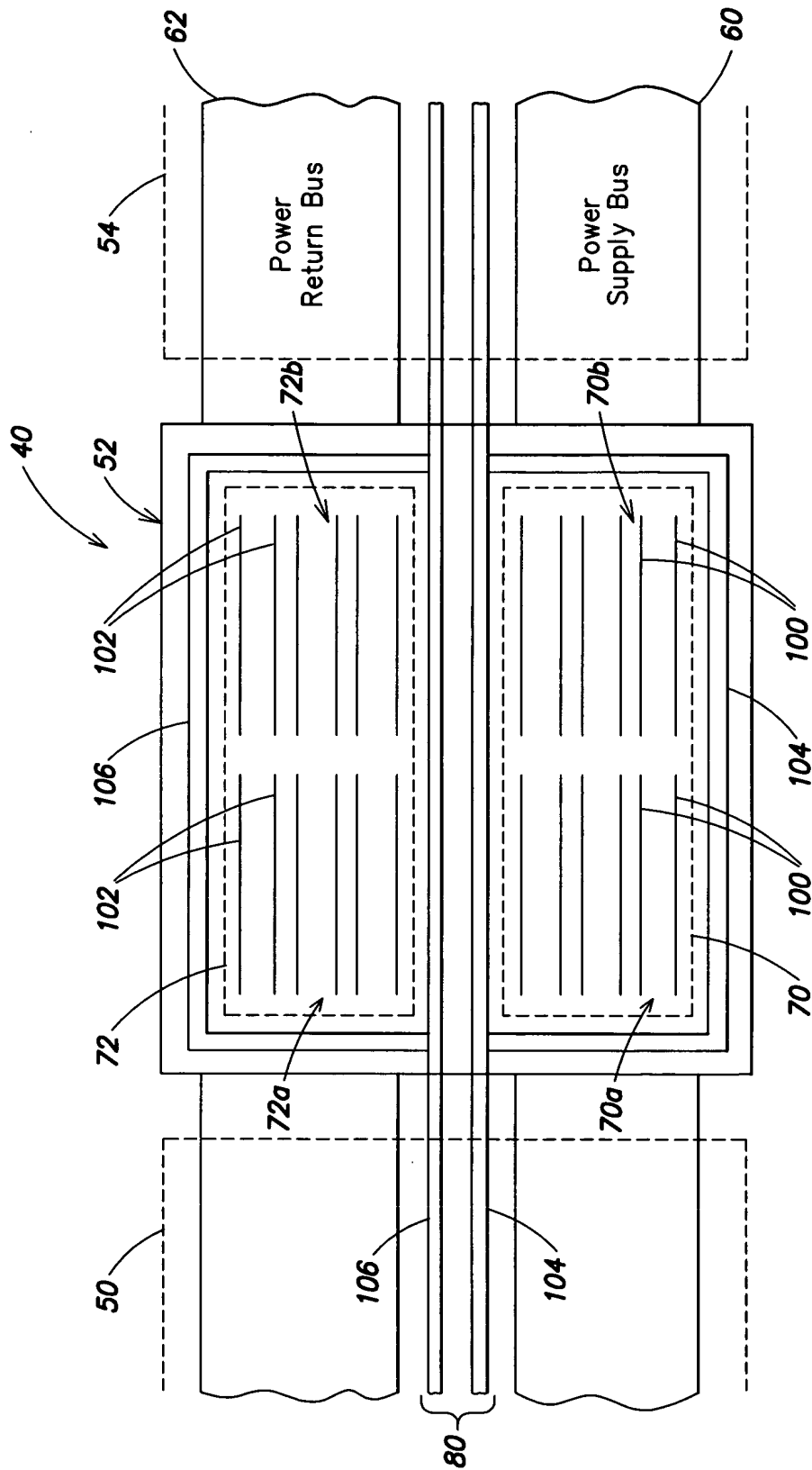


FIG. 3

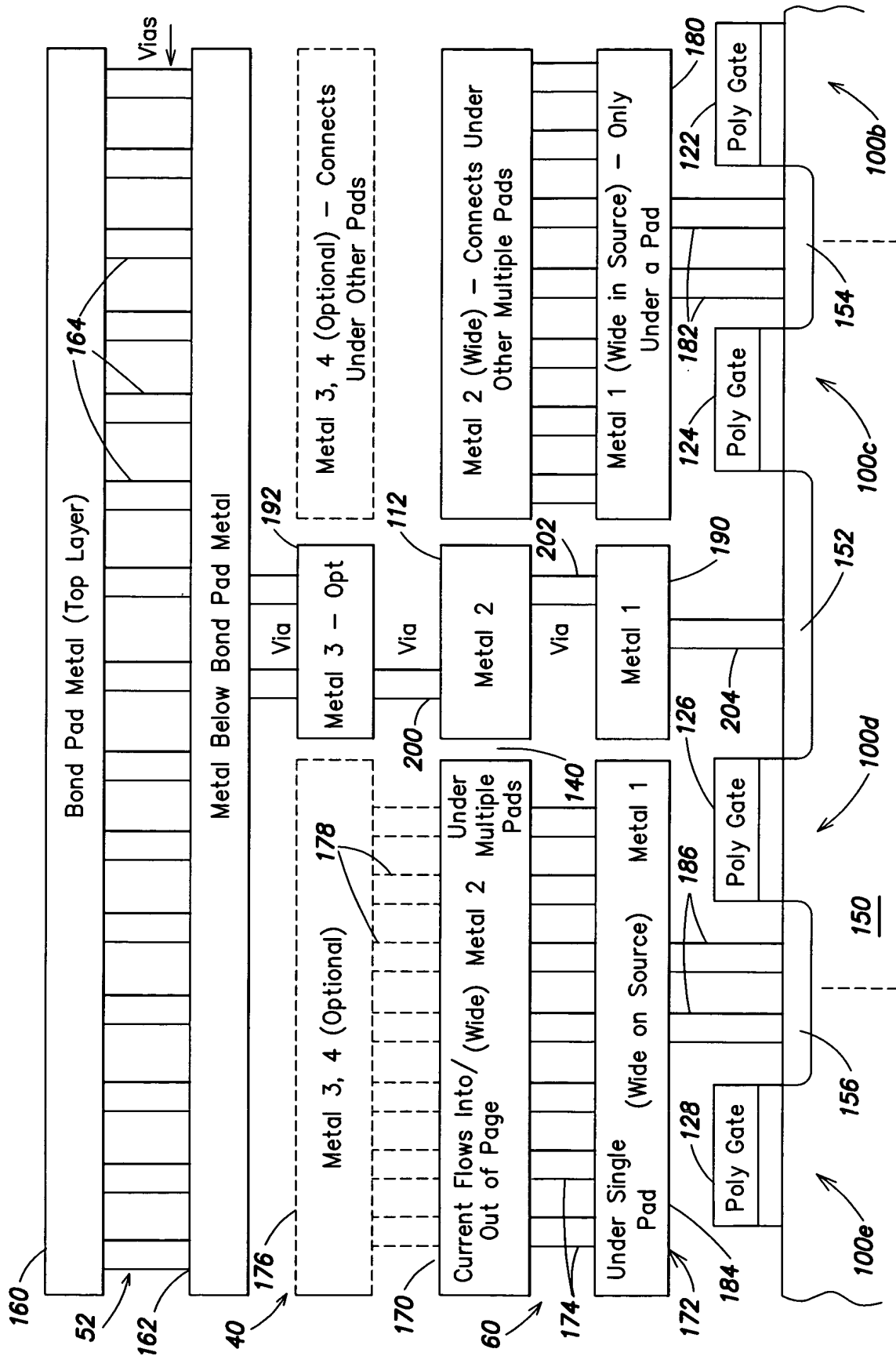


FIG. 5

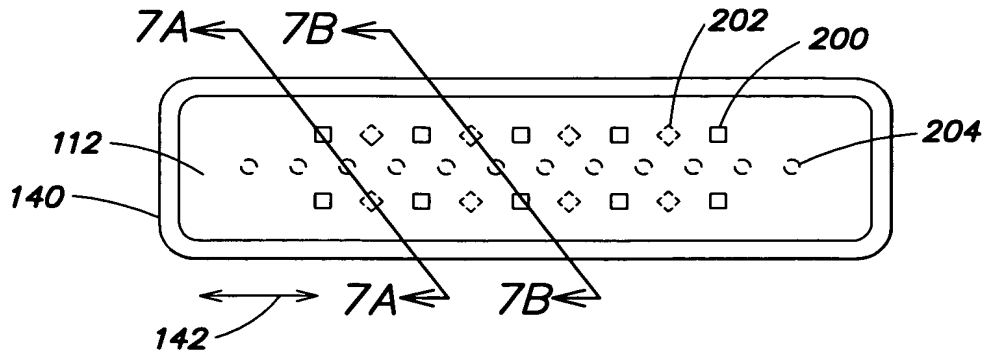


FIG. 6

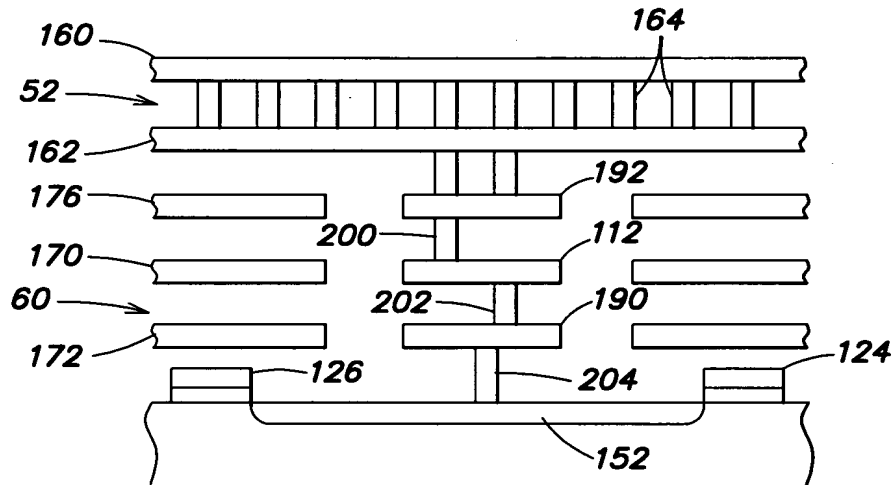


FIG. 7A

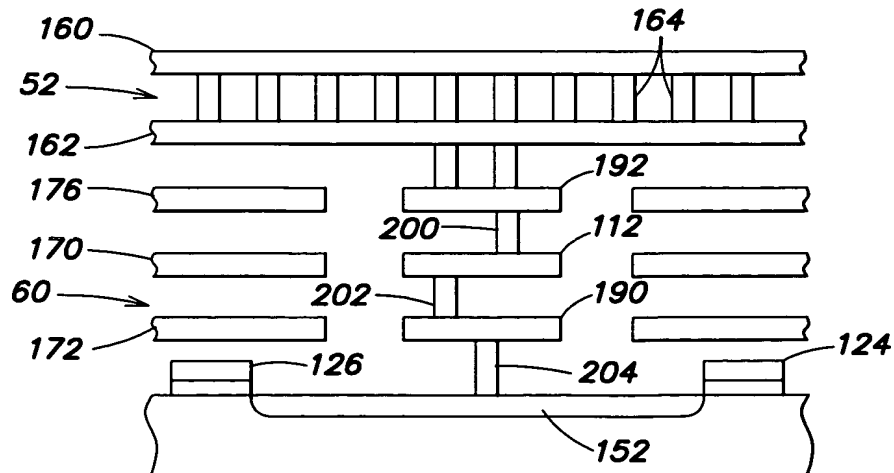


FIG. 7B

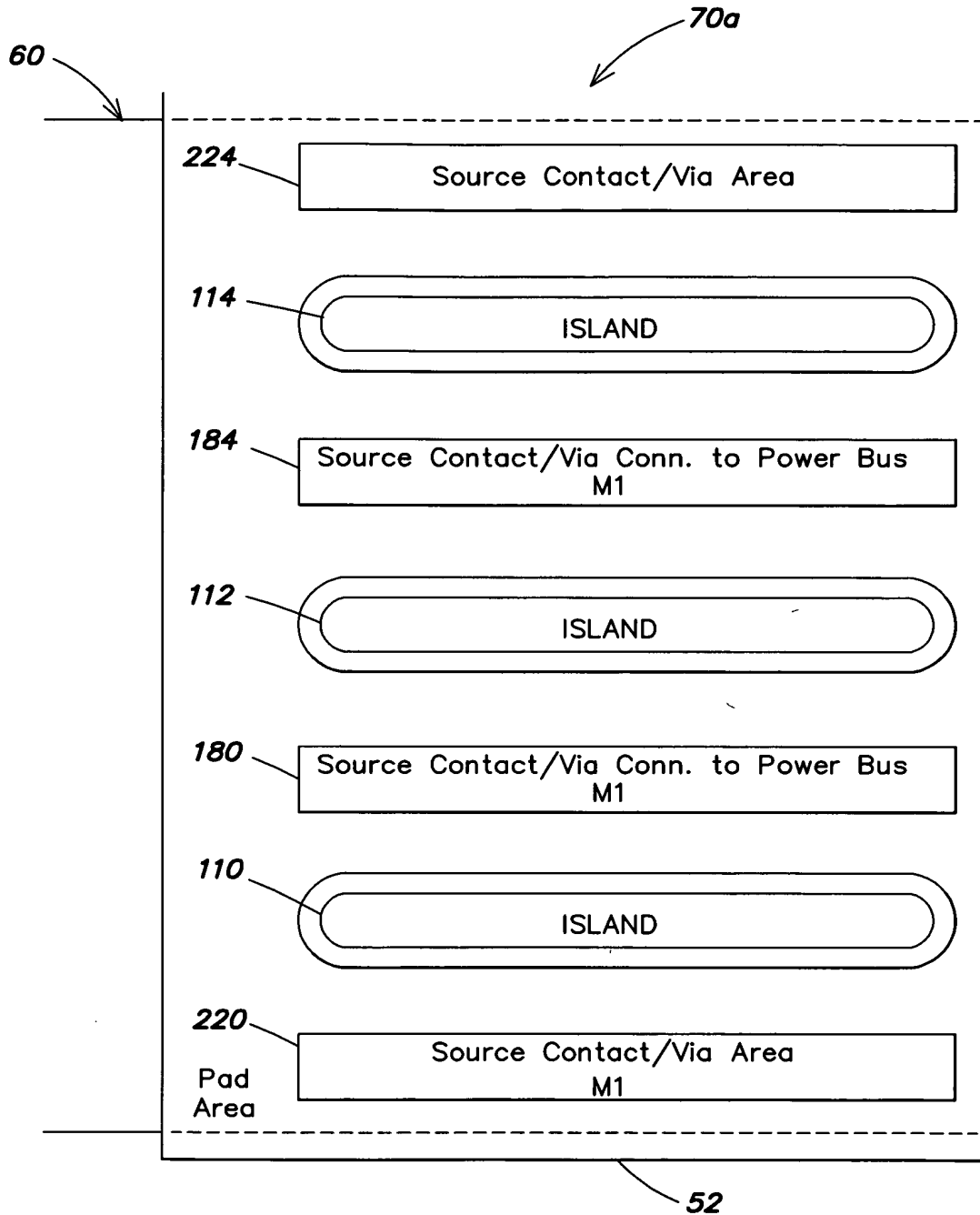


FIG. 8

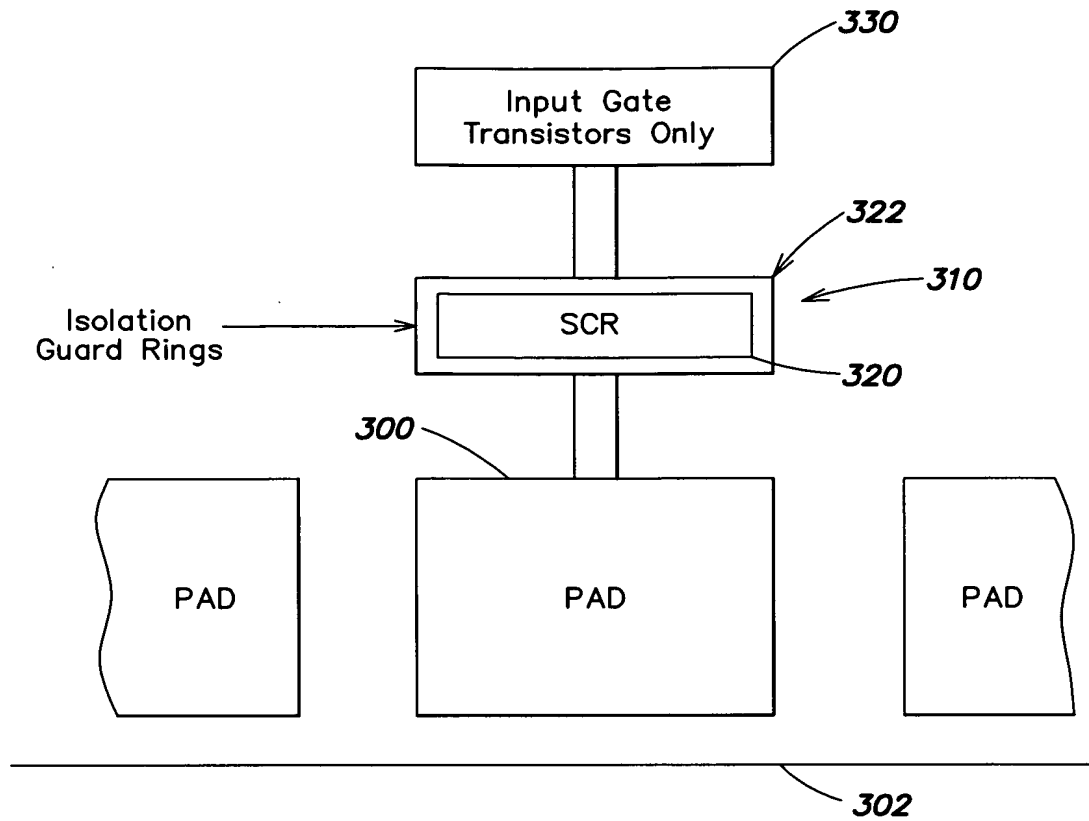


FIG. 9
(Prior Art)

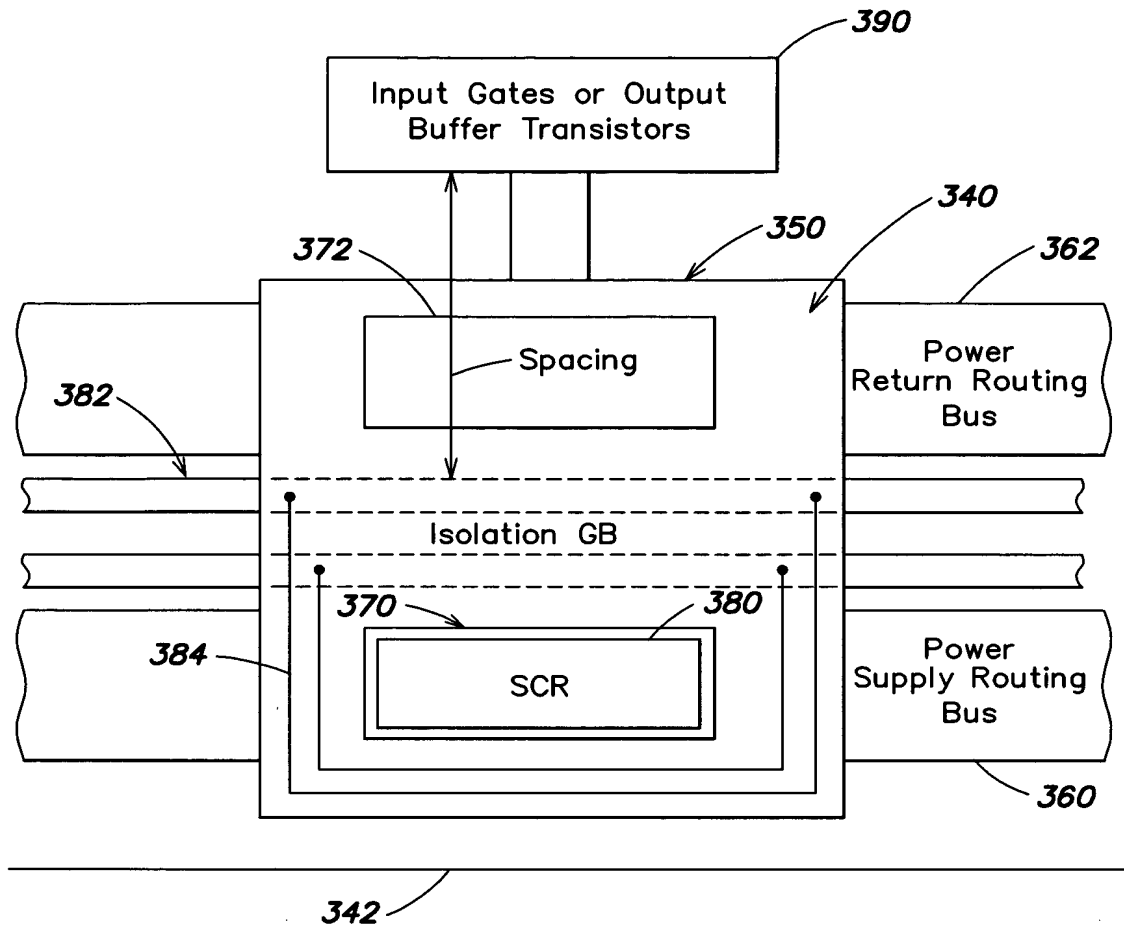


FIG. 10

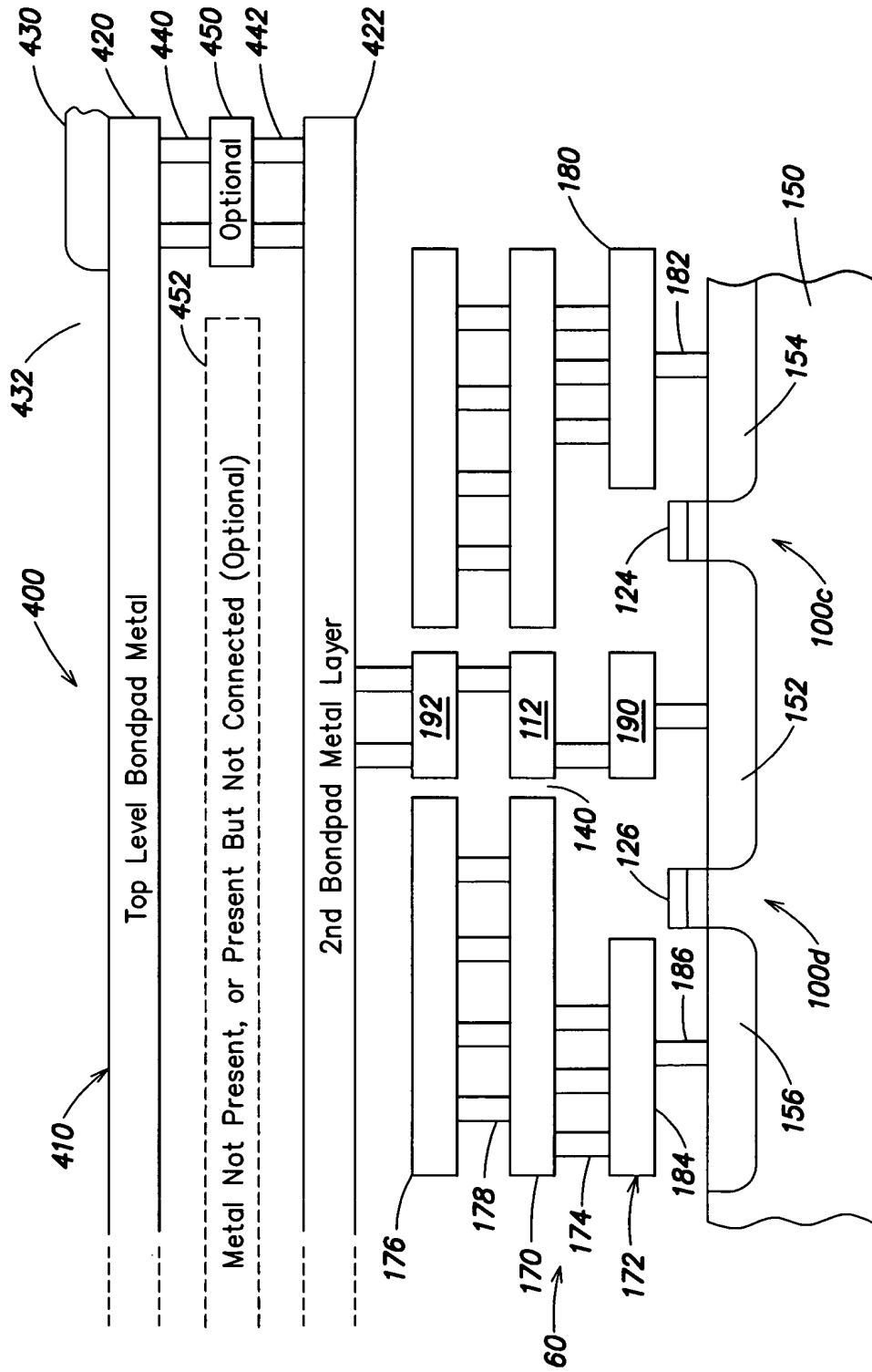


FIG. 11